

## Tack Flux No-Clean in Jar 75g

### Product Highlights

- Ideal for all rework, solder, de-solder and reflow applications
- Non-corrosive, non-conductive, no-clean
- Tack flux will not run all over PCB when applied
- Has a pleasant odor
- Excellent wetting
- Easily cleaned with isopropyl alcohol (IPA)
- Attachment of BGA spheres
- Soldering flip chip components
- Long stencil life
- Wide process window
- Clear residue
- Can be used with Leaded and Lead-Free applications
- RoHS II and REACH compliant

### Specifications

|                      |  |
|----------------------|--|
| Flux Type:           | Synthetic No-Clean (for Leaded and Lead-Free applications) |
| Flux Classification: | RELO   |
| Packaging:           | Jar 75g  |
| Shelf Life:          | Refrigerated >24 months, Unrefrigerated >24 months         |

### Stencil Life

- >8 hours @ 20-50% RH 22-28°C (72-82°F)
- >4 hours @ 50-70% RH 22-28°C (72-82°F)

### Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

### Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Do not freeze. Allow 4 hours for flux to reach an operating temperature of 20-25°C (68-77°F) before use.

### Conforms to the following Industry Standards:

|  |     |
|--|-----|
| J-STD-004B, Amendment 1 (Solder Fluxes): | Yes |
| RoHS 2 Directive 2011/65/EU:             | Yes |